# **Dual General Purpose Transistor**

## **PNP Dual**

This transistor is designed for general purpose amplifier applications. It is housed in the SOT-563 which is designed for low power surface mount applications.

- Lead-Free Solder Plating
- Low  $V_{CE(SAT)}$ , < 0.5 V

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	-60	V
Collector - Base Voltage	$V_{CBO}$	-50	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	V
Collector Current – Continuous	I <sub>C</sub>	-100	mAdc

## THERMAL CHARACTERISTICS

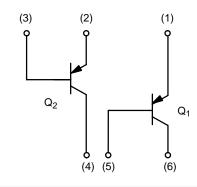
Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$	P <sub>D</sub>	357 (Note 1)	mW
Derate above 25°C		2.9 (Note 1)	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	350 (Note 1)	°C/W
Characteristic			
(Both Junctions Heated)	Symbol	mbol Max	
Total Device Dissipation T <sub>A</sub> = 25°C	P <sub>D</sub>	500	mW
Derate above 25°C		(Note 1) 4.0 (Note 1)	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	250 (Note 1)	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

<sup>1.</sup> FR-4 @ Minimum Pad.



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## MARKING DIAGRAM

3M D



SOT-563 CASE 463A Style 2

3M = Specific Device Code

## **ORDERING INFORMATION**

D = Date Code

Device	Package	Shipping†
EMT2DXV6T5	SOT-563	2 mm Pitch 8000/Tape & Reel

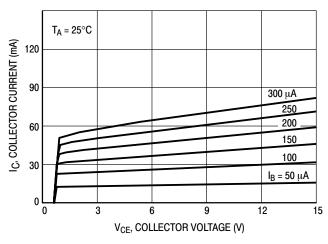
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** $(T_A = 25^{\circ}C)$

Characteristic	Symbol	Min	Тур	Max	Unit
Collector–Base Breakdown Voltage (I <sub>C</sub> = -50 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-60	-	-	Vdc
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-50	-	-	Vdc
Emitter–Base Breakdown Voltage ( $I_E = -50 \mu Adc, I_E = 0$ )	$V_{(BR)EBO}$	-6.0	-	-	Vdc
Collector–Base Cutoff Current (V <sub>CB</sub> = -30 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-0.5	nA
Emitter-Base Cutoff Current (V <sub>EB</sub> = -5.0 Vdc, I <sub>B</sub> = 0)	I <sub>EBO</sub>	-	-	-0.5	μΑ
Collector–Emitter Saturation Voltage (Note 2) $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	-	-	-0.5	Vdc
DC Current Gain (Note 2) (V <sub>CE</sub> = -6.0 Vdc, I <sub>C</sub> = -1.0 mAdc)	h <sub>FE</sub>	120	-	560	-
Transition Frequency ( $V_{CE} = -12 \text{ Vdc}$ , $I_{C} = -2.0 \text{ mAdc}$ , $f = 30 \text{ MHz}$ )	f <sub>T</sub>	_	140	_	MHz
Output Capacitance ( $V_{CB} = -12 \text{ Vdc}$ , $I_E = 0 \text{ Adc}$ , $f = 1 \text{ MHz}$ )	C <sub>OB</sub>	-	3.5	-	pF

<sup>2.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, D.C.  $\leq$  2%.

## TYPICAL ELECTRICAL CHARACTERISTICS



1000

T<sub>A</sub> = 75°C

T<sub>A</sub> = 25°C

T<sub>A</sub> = 25°C

T<sub>A</sub> = 25°C

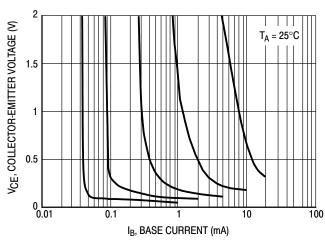
T<sub>A</sub> = 25°C

T<sub>A</sub> = 75°C

T<sub>A</sub> = 75°C

Figure 1. I<sub>C</sub> – V<sub>CE</sub>

Figure 2. DC Current Gain



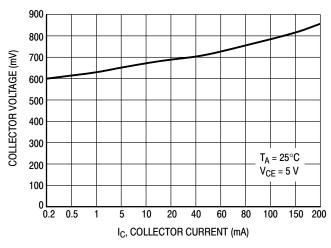
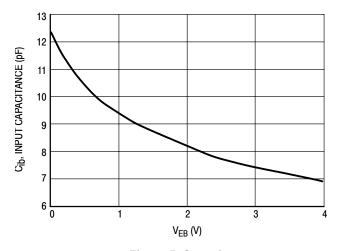


Figure 3. Collector Saturation Region

Figure 4. On Voltage



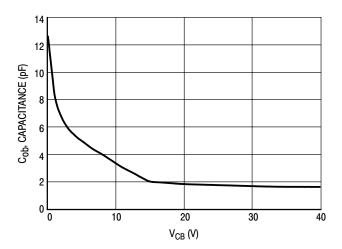
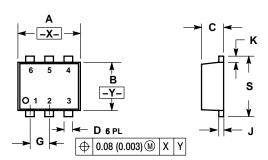


Figure 5. Capacitance

Figure 6. Capacitance

## PACKAGE DIMENSIONS

SOT-563, 6-LEAD CASE 463A-01 ISSUE D



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES
  LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.50	1.70	0.059	0.067
В	1.10	1.30	0.043	0.051
C	0.50	0.60	0.020	0.024
D	0.17	0.27	0.007	0.011
G	0.50 BSC		0.020 BSC	
J	0.08	0.18	0.003	0.007
K	0.10	0.30	0.004	0.012
S	1.50	1.70	0.059	0.067

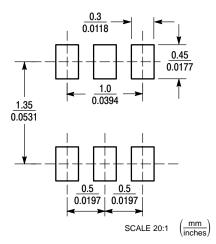
#### STYLE 2:

- PIN 1. EMITTER 1 2. EMITTER 2
  - 3 BASE 2

  - 4. COLLECTOR 2

  - 5. BASE 1 6. COLLECTOR 1

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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